

L Number	Hits	Search Text	DB	Time stamp
1	249	((semiconductor die chip ic (integrated adj circuit) dice) same (heat adj2 (sink spreader radiate radiating radiation element metal cover lid slug)) same (substrate carrier board pcb cb pb ((printed circuit) adj3 board)) same (ground grounding grounded)) same (bga pbga ball bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/06 18:08